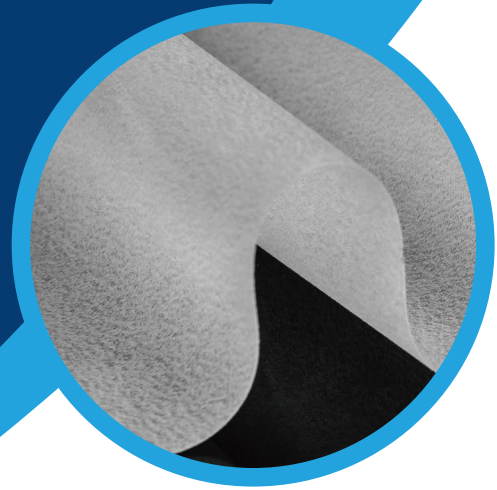


# HI802 & HI802P

## HJT INTEGRATED ENCAPSULATION FILM

HI802 and HI802P are integrated films for HJT cell encapsulation. The integrated film can reduce delamination after aging and has perfect shaping effect on solder strip when laminating. The Film also has positioning function on solder strip so as to reduce the process of low temperature welding and reduce the use of silver paste.



### Category

Item	Normal Spec	Customized Spec
Thickness	0.45~0.6mm	0.2~0.8mm
Width	970~1297mm	300~1300mm
Length	300m	150~450m

### Technical Properties

Items		Unit	Test Standard	HI802	HI802P
Model/Using Instruction		/	/	High Transmission	UV Cut Off
Shrinkage Ratio	MD	%	GB/T29848	<3.0	<3.0
	TD	%	GB/T29848	<1.5	<1.5
Light Transmittance	280~380nm	%	GB/T29848	>80	<20
	380~1100nm	%	GB/T29848	>90	>90
Peel Strength	Glass	N/cm	GB/T29848	>80	>80
	HJT Cell	N/cm	Baijia Method	>40	>40
Crosslink Degree		%	GB/T29848	>75	>75
Volume Resistivity		$\Omega$ -cm	GB/T29848	$>1*10^{15}$	$>1*10^{15}$
Aging Properties PCT 48h 121°C 100RH	Yellowness Index	$\Delta$ YI	GB/T29848	<3.0	<3.0
	HJT Cell	N/cm	Baijia Method	>30	>30
UV Aging Test	30kW/h 60°C	$\Delta$ YI	GB/T2984	<3.0	<3.0

### Laminating Process

Laminated Parameters		Temperature (°C)	Vacuum Time (S)	Lamination Time (S)
Single Chamber Laminator		142~148	300~360	900±180
Double Chamber Laminator	A Cavity	125±10	300±60	300±60
	The Second Chamber	148±10	60±30	540±60

The technical parameters in Betterial product manual are for reference only. Technical specifications are subject to change without any prior notice.

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